



Spec No. :DS-70-96-0016 Effective Date: 08/09/2017

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4



1. DESCRIPTION

1.1 Features

- Current transfer ratio (CTR: MIN. 50% at I_F = 5mA, V_{CE} = 5V)
- High input-output isolation voltage (V_{iso} = 5,000Vrms)
- Response time (tr : TYP. $4\mu s$ at $V_{CE} = 2V$, $I_C = 2mA$, $R_L = 100\Omega$)
- Dual-in-line package :

LTV-817: 1-channel type

LTV-827: 2-channel type

LTV-847: 4-channel type

■ Wide lead spacing package :

LTV-817M: 1-channel type

LTV-827M: 2-channel type

LTV-847M: 4-channel type

■ Surface mounting package :

LTV-817S : 1-channel type

LTV-827S : 2-channel type

LTV-847S : 4-channel type

■ Tape and reel packaging :

LTV-817S-TA: 1-channel type

LTV-817S-TA1: 1-channel type

LTV-817S-TP: 1-channel type

LTV-827S-TA: 2-channel type

LTV-827S-TA1: 2-channel type

■ Safety approval

UL 1577

VDE DIN EN60747-5-5 (VDE 0884-5)

CSA CA5A

CQC GB4943.1-2011/ GB8898-2011 (meet Altitude up to 5000m)

Nordic Safety (FIMKO/NEMKO/SEMKO/DEMKO)

BSI

■ RoHS Compliance

All materials be used in device are followed EU RoHS directive (No. 2011/65/EU).

- ESD pass HBM 8000V/MM2000V
- MSL class1

1.2 Applications

- Hybrid substrates that require high density mounting.
- Programmable controllers



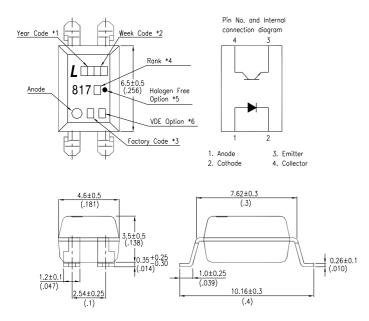
2. PACKAGE DIMENSIONS

2.1 LTV-817

Pin No. and Internal Year Code *1 connection diagram connection diagram Year Code * Rank *4 6.5±0.5 (.256) Halogen Free Option *5 817 🗗 817□• Anode VDE Option *6 VDE Option *6 Factory Code *3 Factory Code *3 3. Emitter 3. Emitter 1. Anode 2. Cathode 4. Collector 7.62±0.3 4.6±0.5 (.181) (.3) 7.62±0.3 (.3) 3.5±0.5 (.138) 6.9±0.5 (0.272) 0.5±0.1 (.02) $7.62 \sim 9.98$ 10.16±0.5 2.54±0.25

2.2 LTV-817M

2.3 LTV-817S



Notes:

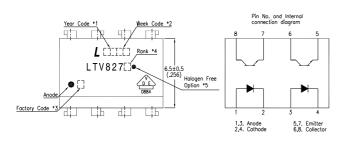
- 1. 2-digit year code, example : 2016 = 16
- 2. 2-digit work week ranging from '01' to '53'
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- 5. "●" for halogen free option.
- 6. "4"or"V" for VDE option.

Dimensions in millimeters(inches).

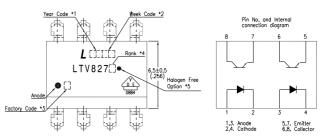


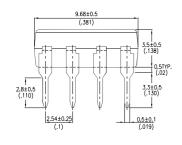


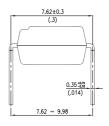
2.4 LTV-827

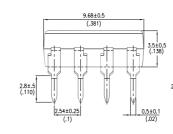


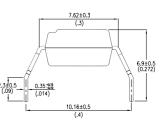
2.5 LTV-827M



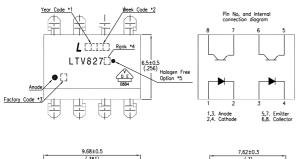


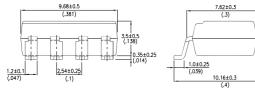






2.6 LTV-827S





Notes:

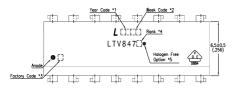
- 1. 2-digit year code, example : 2016 = 16
- 2. 2-digit work week ranging from '01' to '53'
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- 5. "●" for halogen free option.

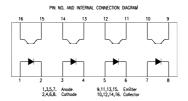
Dimensions in millimeters(inches).

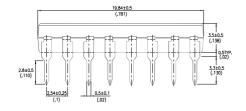


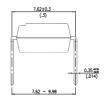


2.7 LTV-847

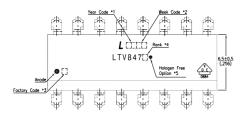


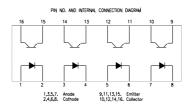


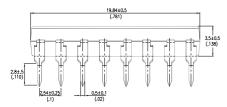


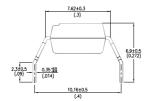


2.8 LTV-847M

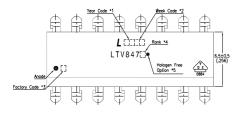


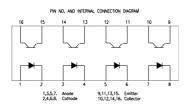


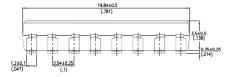


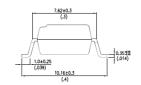


2.9 LTV-847S









Notes:

- 1. 2-digit year code, example : 2016 = 16
- 2. 2-digit work week ranging from '01' to '53'
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. Rank shall be or shall not be marked.
- 5. "●" for halogen free option.

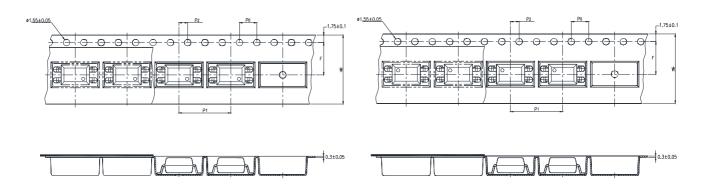
Dimensions in millimeters(inches).



3. TAPING DIMENSIONS

3.1 LTV-817S-TA

3.2 LTV-817S-TA1



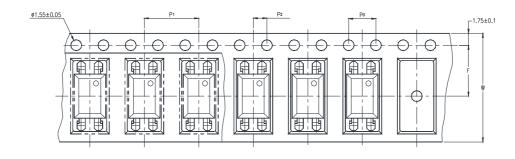
Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P ₀	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	12±0.1 (0.472)

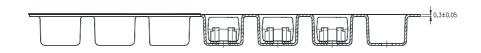
3.3 Quantities Per Reel

Package Type	TA/TA1
Quantities (pcs)	1000



3.4 LTV-817S-TP





Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P ₀	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	8±0.1 (0.472)

3.5 Quantities Per Reel

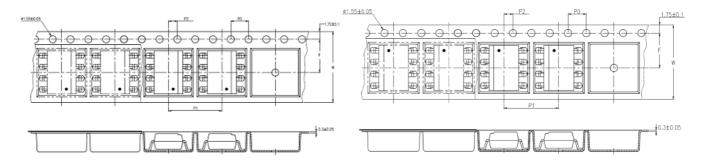
Package Type	TP
Quantities (pcs)	2000





3.6 LTV-827S-TA

3.7 LTV-827S-TA1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P_0	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	12±0.1 (0.472)

3.8 Quantities Per Reel

Package Type	TA/TA1
Quantities (pcs)	1000



4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25℃

	Parameter	Symbol	Rating	Unit
	Forward Current	I _F	50	mA
	Reverse Voltage	V_R	6	V
	Power Dissipation	Р	70	mW
Input	Peak Forward Current (100µs pulse, 100Hz frequency)	IFP	1	А
	Thermal Resistance Junction-Ambient	Rth_{J-A}	325	°C/W
	Thermal Resistance Junction-Case	Rth_{J-C}	200	°C/W
	Collector - Emitter Voltage	V_{CEO}	35	V
Output	Emitter - Collector Voltage		6	V
Output	Collector Current	I _C	50	mA
	Collector Power Dissipation		150	mW
	Total Power Dissipation	P _{tot}	200	mW
1.	Isolation Voltage	V _{iso}	5000	V_{rms}
	Operating Temperature (LTV-827/847)	T_{opr}	-30 ~ +100	°C
	Operating Temperature (LTV-817)	T_{opr}	-55 ~ +110	°C
	Storage Temperature	T_{stg}	-55 ~ +125	°C
	Soldering Temperature	T_{sol}	260	°C

1. AC For 1 Minute, R.H. = $40 \sim 60\%$

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.



4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25℃

Parameter		Symbol	Min.	Тур.	Max.	Unit	Test Condition
	Forward Voltage	V _F	_	1.2	1.4	V	I _F =20mA
Input	Reverse Current	I _R	_	_	10	μА	V _R =4V
	Terminal Capacitance	Ct	_	30	250	pF	V=0, f=1KHz
	Collector Dark Current	I _{CEO}	_	_	100	nA	V _{CE} =20V, I _F =0
Output	Collector-Emitter Breakdown Voltage	BV _{CEO}	35	_	_	V	I _C =0.1mA, I _F =0
	Emitter-Collector Breakdown Voltage	BV _{ECO}	6	_	_	V	I _E =10μΑ, I _F =0
	Collector Current	Ic	2.5	_	30	mA	L 5 A . V 5 V
	Current Transfer Ratio	CTR	50	_	600	%	I _F =5mA, V _{CE} =5V
	Collector-Emitter Saturation Voltage	V _{CE(sat)}	_	0.1	0.2	V	I _F =20mA, I _C =1mA
TRANSFER	Isolation Resistance	R _{iso}	5×10 ¹⁰	1×10 ¹¹	_	Ω	DC500V, 40 ~ 60% R.H.
CHARACTERISTICS	Floating Capacitance	Cf	_	0.6	1	pF	V=0, f=1MHz
	Cut-off Frequency	fc	_	80	_	kHz	VCE=5V, IC=2mA RL=100Ω,-3dB
	Response Time (Rise)	tr	_	4	18	μs	V _{CE} =2V, I _C =2mA
	Response Time (Fall)	tf	_	3	18	μs	R_L =100 Ω ,

1. CTR =
$$\frac{I_C}{I_F} \times 100\%$$





5. RANK TABLE OF CURRENT TRANSFER RATIO

	CTR Rank	Min	Max	Condition
	L	50	100	
	A	80	160	
LTV-817	В	130	260	
L1 V-017	С	200	400	
	D	300	600	
	L or A or B or C or D	50	600	
	No Bin	50	600	
	В	130	260	I _F =5mA, V _{CE} =5V, Ta=25°C
LTV-827	С	200	400	
L1 V-027	D	300	600	
	BC	130	400	
	CD	200	600	
	No Bin	50	600	
LTV-847	ВС	130	400	
	CD	200	600	



6. CHARACTERISTICS CURVES

Fig.1 Forword Current

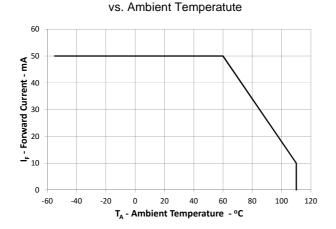


Fig.3 Collector-emitter Saturation Voltage vs. Forward Current

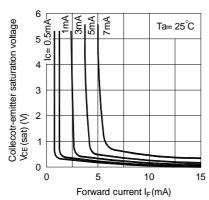


Fig.5 Current Transfer Ratio vs.
Forward Current

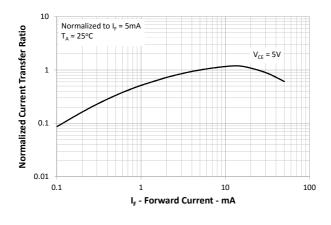


Fig.2 Collector Power Dissiption vs. Ambient Temperature

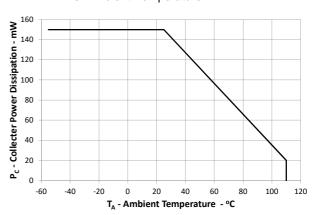


Fig.4 Forward Current vs. Forward Voltage

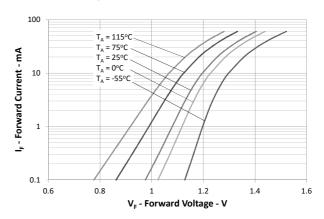


Fig.6 Collector Current vs.

Collector-emitter Voltage

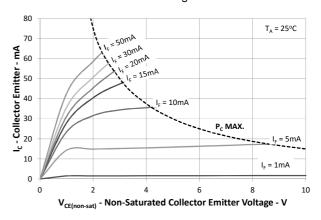




Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature

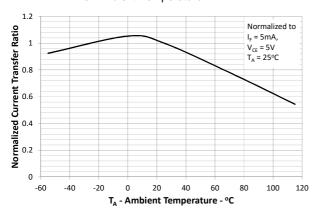


Fig.9 Collector Dark Current vs.
Ambient Temperature

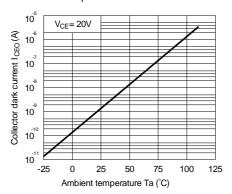


Fig.11 Frequency Response

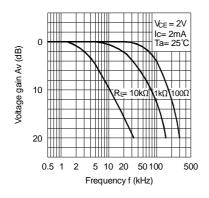


Fig.8 Collector-emitter Saturation Voltage vs. Ambient Temperature

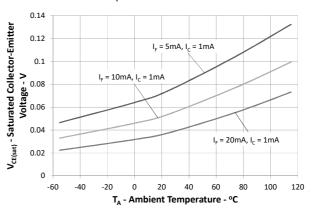
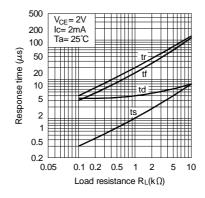
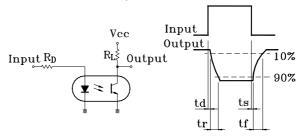


Fig.10 Response Time vs. Load

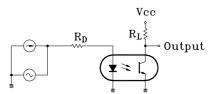
Resistance



Test Circuit for Response Time



Test Circuit for Frequency Response



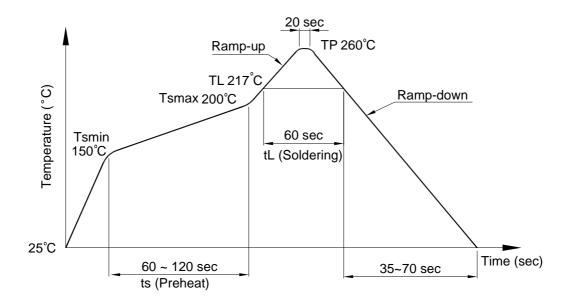


7. TEMPERATURE PROFILE OF SOLDERING

7.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions	
Preheat		
- Temperature Min (T _{Smin})	150°C	
- Temperature Max (T _{Smax})	200°C	
- Time (min to max) (ts)	90±30 sec	
Soldering zone		
- Temperature (T _L)	217°C	
- Time (t _L)	60 sec	
Peak Temperature (T _P)	260°C	
Ramp-up rate	3°C / sec max.	
Ramp-down rate	3~6°C / sec	







7.2 Wave soldering (JEDEC22A111 compliant)

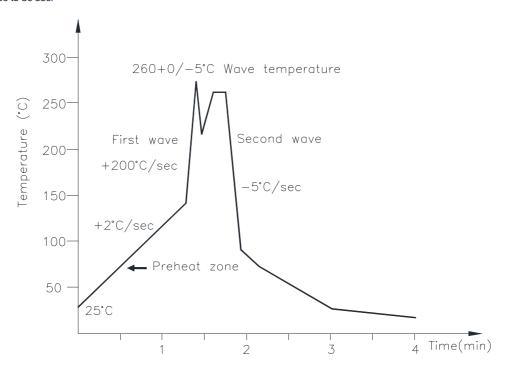
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



7.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

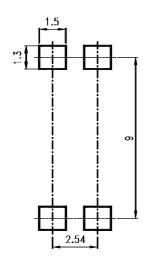
Temperature: 380+0/-5°C

Time: 3 sec max.

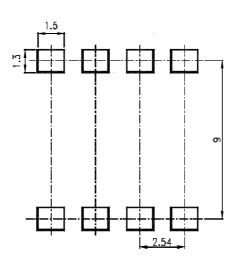


8. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

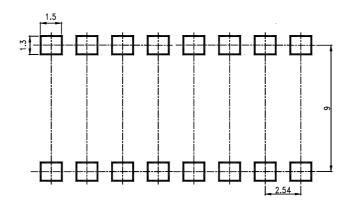
8.1 4 PIN



8.28 PIN



8.3 16PIN

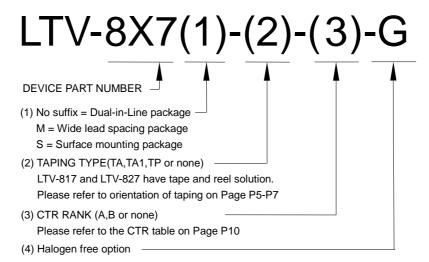


Note:

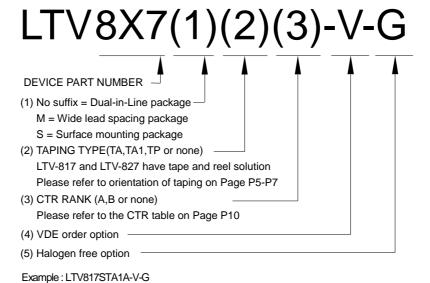
Dimensions in millimeters.



9. Naming rule



Example: LTV-817S-TA1-A-G







10. Notes:

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.
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